

1.25mm Density NON-ZIF FPC Connectors CEM-B56 Series

FEATURES

1. These are very low profile connectors for FPC (Flexible Printed Circuit) with surface mount contacts.
2. Contacts are designed as a gastight single-face contact system.
3. The contact pitch is 1.25mm, and terminals are arranged zigzag with an inter-line space of 2.5mm.



HOW TO ORDER

B56-005-02 0-HJCA

- 1 Series No.
 2 No. of contacts (005 : 5pins)
 3 Housing material (02 : PBT resin)
 4 UL grade (0 : UL94V-0)
 5 Supplementary symbol

SPECIFICATIONS

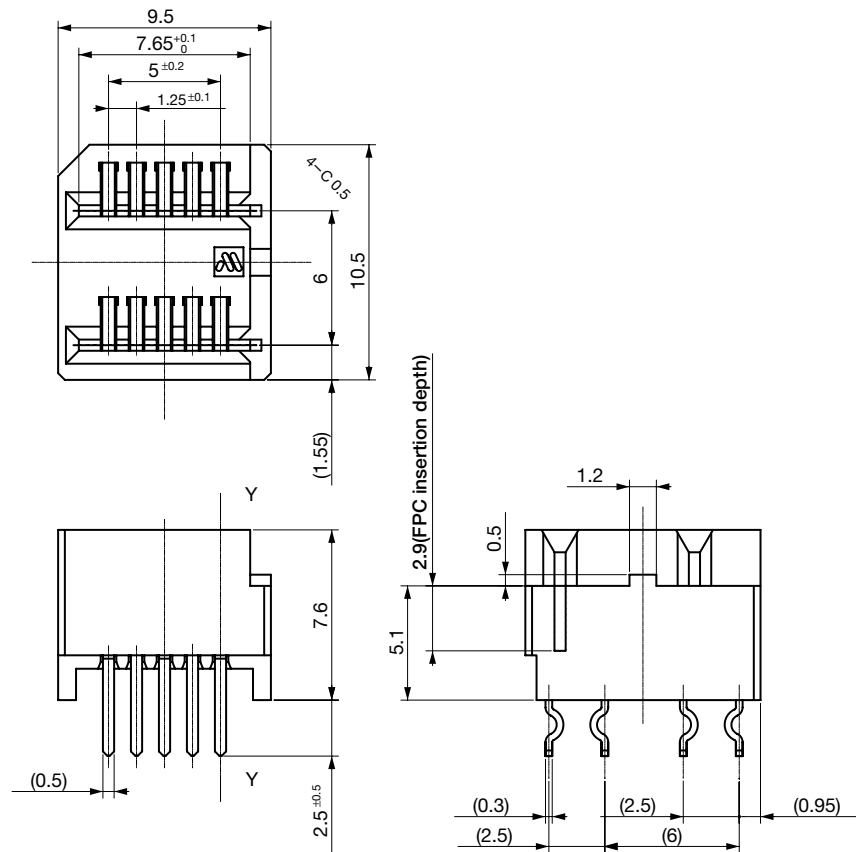
ELECTRICAL CHARACTERISTICS & MECHANICAL CHARACTERISTICS

Rated Voltage	AC 200V (rms)
Rated Current	1A
Withstanding Voltage	500V AC (rms) 1minute
Insulation Resistance	500MΩ min. (at 500V DC)
Contact Resistance	30mΩ max.
Applicable FPC Thickness	0.3±0.05mm

MATERIAL & FINISH

Component Parts	Material	Finish
Housing	Glass filled PBT resin	—
Contact	Copper Alloy	Solder plating

DIMENSIONS



Unit : mm